MOSFETs Silicon N-channel MOS (U-MOSIX-H)

TPH2R506PL

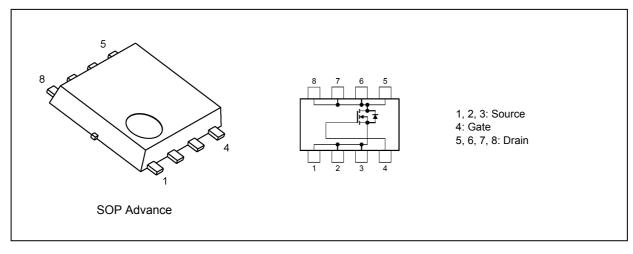
1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators
- Motor Drivers

2. Features

- (1) High-speed switching
- (2) Small gate charge : Q_{SW} = 19 nC (typ.)
- (3) Small output charge : $Q_{oss} = 51 \text{ nC}$ (typ.)
- (4) Low drain-source on-resistance : $R_{DS(ON)}$ =1.9 mO (typ.)(V_{GS} = 10 V)
- (5) Low leakage current : $I_{\rm DSS}$ = 10 μA (max)(V_{\rm DS} = 60 V)
- (6) Enhancement mode : V_{th} = 1.5 to 2.5 V (V_{DS} = 10 V, I_D = 0.5 mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) (T_a = 25 °C unless otherwise specified)

Characterist	Symbol	Rating	Unit		
Drain-source voltage			V _{DSS}	60	V
Gate-source voltage			V _{GSS}	±20	
Drain current (DC)	(T _c = 25 °C)	(Note 1)	Ι _D	100	A
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I _D	160]
Drain current (pulsed)	(t = 100 µs)	(Note 1)	I _{DP}	500	
Power dissipation	(T _c = 25 °C)		PD	132	w
Power dissipation		(Note 3)	PD	3.0	
Power dissipation		(Note 4)	PD	0.96	
Single-pulse avalanche energy		(Note 5)	E _{AS}	65	mJ
Single-pulse avalanche current		(Note 5)	I _{AS}	100	A
Channel temperature			T _{ch}	175	°C
Storage temperature			T _{stg}	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit		
Channel-to-case thermal resistance	(T _c = 25 °C)		R _{th(ch-c)}	1.13	°C/W
Channel-to-ambient thermal resistance	(T _a = 25 °C)	(Note 3)	R _{th(ch-a)}	50	
Channel-to-ambient thermal resistance	(T _a = 25 °C)	(Note 4)	R _{th(ch-a)}	156	

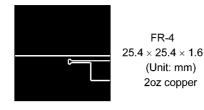
Note 1: Ensure that the channel temperature does not exceed 175 °C.

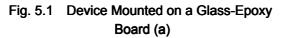
Note 2: Limited by silicon chip capability.

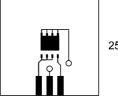
Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: V_DD = 48 V, T_ch = 25 °C (initial), L = 5 μ H, I_{AS} = 100 A







FR-4 25.4 × 25.4 × 1.6 (Unit: mm) 2oz copper

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25 °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V	_	_	±0.1	μA
Drain cut-off current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V			10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	60		_	V
Drain-source breakdown voltage (Note 6)	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	45		_	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 0.5 mA	1.5		2.5	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 4.5 V, I _D = 30 A		2.8	4.4	mΩ
		V _{GS} = 10 V, I _D = 50 A	_	1.9	2.5	

Note 6: If a reverse bias is applied between gate and source, this device enters V_{(BR)DSX} mode. Note that the drainsource breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics ($T_a = 25$ °C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 30 V, V _{GS} = 0 V,	_	4180	5435	pF
Reverse transfer capacitance	C _{rss}	f = 1 MHz	_	60	115	
Output capacitance	C _{oss}		_	770	_	
Gate resistance	r _g	—	—	0.6	1.1	Ω
Switching time (rise time)	tr	See Figure 6.2.1	_	7.1	—	ns
Switching time (turn-on time)	t _{on}		_	16	_	
Switching time (fall time)	t _f]		13	_	
Switching time (turn-off time)	t _{off}		_	39	_	

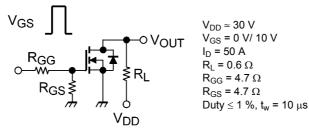


Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics ($T_a = 25$ °C unless otherwise specified)

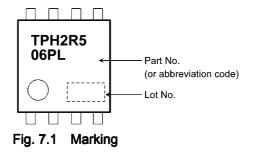
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$\label{eq:VDD} \begin{array}{l} V_{DD} \approx 30 \ V, \ V_{GS} \texttt{=} 10 \ V, \\ I_{D} \texttt{=} 50 \ A \end{array}$	—	60	—	nC
		$\label{eq:VDD} \begin{array}{l} V_{DD} \approx 30 \ V, \ V_{GS} = 4.5 \ V, \\ I_{D} = 50 \ A \end{array}$	—	32	_	
Gate-source charge 1	Q _{gs1}	$V_{DD} \approx 30$ V, V_{GS} = 10 V,		17	_	
Gate-drain charge	Q _{gd}	I _D = 50 A	_	11	_	
Gate switch charge	Q _{SW}			19		
Output charge	Q _{oss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz		51	_	

6.4. Source-Drain Characteristics (T_a = 25 $^{\circ}$ C unless otherwise specified)

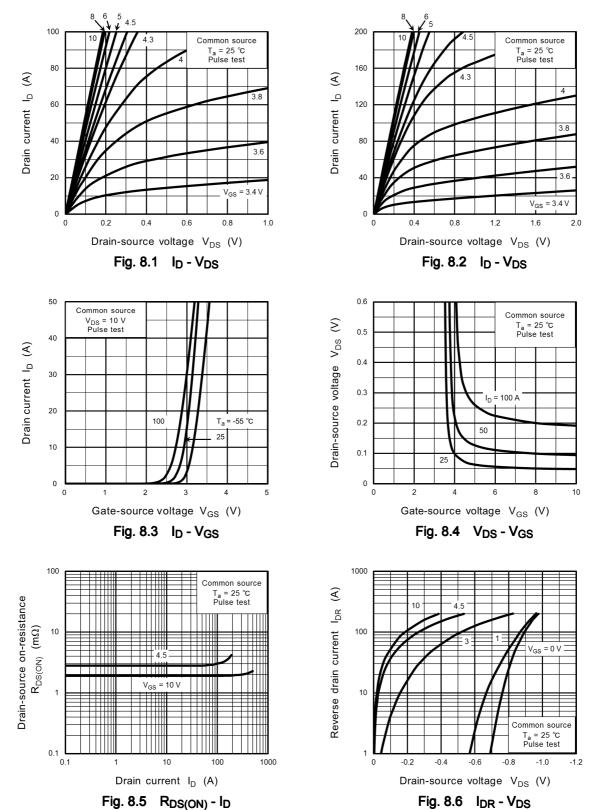
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) (N	Note 7)	I _{DRP}	(t = 100 μs)	_	—	500	А
Diode forward voltage		V _{DSF}	I _{DR} = 100 A, V _{GS} = 0 V	_	_	-1.2	V
Reverse recovery time			I _{DR} = 25 A, V _{GS} = 0 V,	_	49	_	ns
Reverse recovery charge		Q _{rr}	-dl _{DR} /dt = 100 A/μs	—	57	_	nC

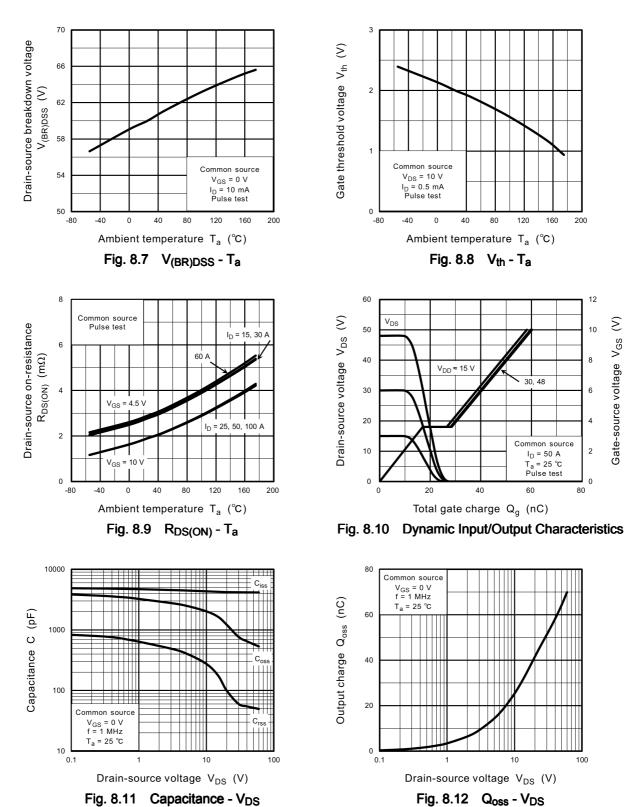
Note 7: Ensure that the channel temperature does not exceed 175 °C.

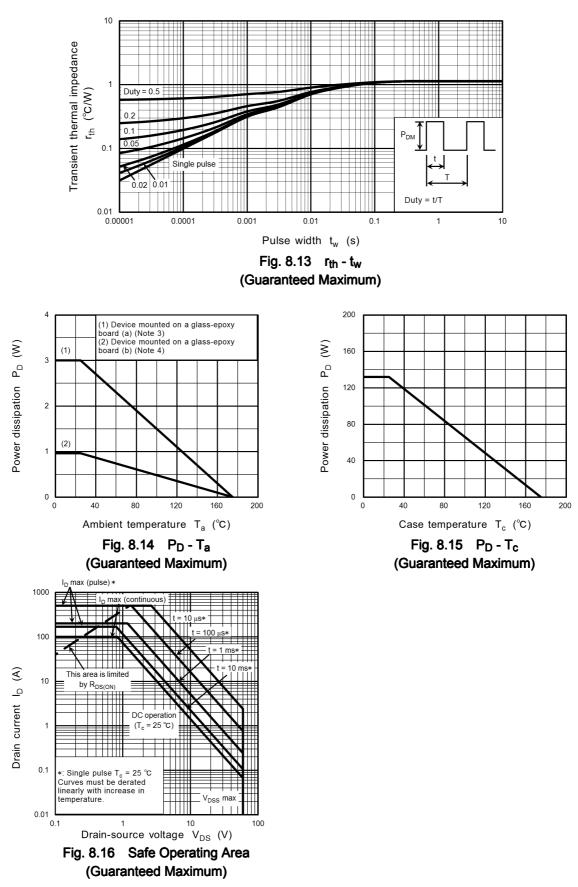
7. Marking



8. Characteristics Curves (Note)







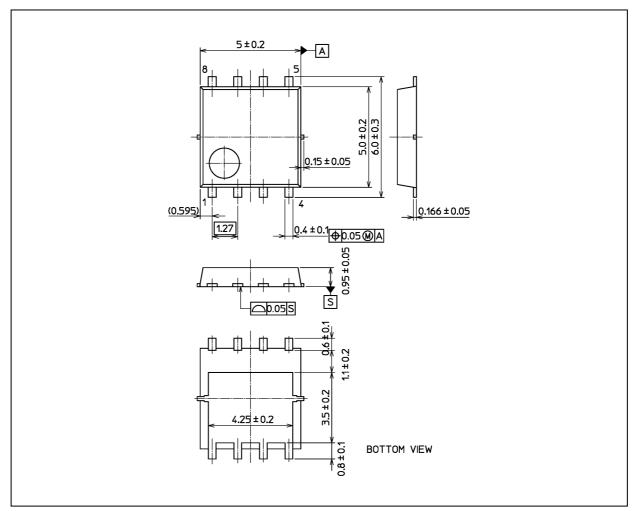
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



TPH2R506PL

Package Dimensions

Unit: mm



Weight: 0.069 g (typ.)

TOSHIBA: 2-5Q1S

Nickname: SOP Advance

Package Name(s)

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